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Features:

- μPower Operation (15 μW typical at 25°C)
- Omni polar (switches with N or S pole)
- 2.5 to 5.5 Volt Operation
- Simple Digital Output Interfacing
CMOS Push-Pull
- Ultra Low Offset Canceling Amplifiers Provide Sensitive, Accurate, Stable Switching Points and Immunity to Mechanical Stress
- Solid State Circuitry
- Operating Temperature Range: -40°C to +85°C
- RoHS Compliant TSOT-23 3 Lead Package

General Description

The MX887P integrated Hall-Effect switch targets the requirements of low-power portable devices with battery operating voltages from 2.5V to 5.5V. On-chip power management circuitry reduces the effective average current to just 5μA at 3.0 V_{SUPPLY}.

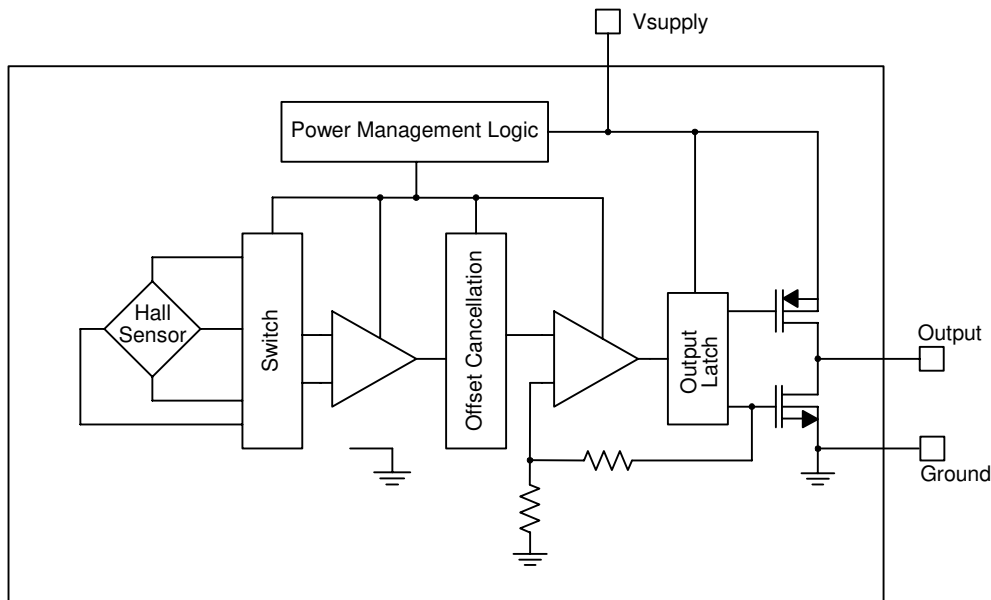
The switch output will transition to the Ground potential when either a north or south magnetic pole is applied. The removal of a magnetic field will transition the switch to the V_{supply} potential. Emulating the behavior of a traditional reed switch, together with the advantages of high integration and solid state reliability, makes the MX887P is an ideal replacement in low-power portable device applications.

Applications:

- Handheld Portable Devices
- White Goods
- Automotive - Body Systems
- Security Systems
- High Reliability Reed Switch Replacement

Ordering Information

Part No.	Description	Qty
MX887PHTR	TSOT-23 3L Tape & Reel	3000

Functional Block Diagram


Pin Description

Pin No.	Pin Name	Description
1	VSUPPLY	2.5 to 5.5 Volt
2	OUT	CMOS Push-Pull
3	GROUND	Ground

Circuit Description

The MX887P μ Power Hall-Effect Switch consists of a Hall element, small signal amplifier, latch, and CMOS push-pull driver. Offset cancellation rejects errors in signal stages and the influence of mechanical stress on the Hall element. This technique together with a precision threshold generator and comparator produce highly accurate magnetic switch points. The Hall element is activated for a small fraction of an operating cycle, then latched in that sample state for the remainder of the period. By using this technique, very low power consumption is achieved.

Electrical Characteristics

Over operating voltage and temperature range unless otherwise noted.

Parameter	Condition	Min	Typ	Max	Unit
Supply Voltage		2.5		5.5	V
Output Leakage Current	$V_{OUT} = 5.5V, BRPN < B < BRPS$		<1.0	1.0	μA
Output On Voltage	$I_{OUT} = 1mA, V_{DD} = 3.0V$		100	300	mV
Awake Time				90	μS
Period				90	mS
Duty Cycle			0.1		%
Supply Current	Awake (enabled)			2.0	mA
	Asleep (disabled)			8.0	μA
	Average (Calculated)		5	15	μA
ESD	Human Body Model	2			kV

- Notes: 1. Operating and release points will vary with supply voltage.
 2. BOPX = operating point (output turns ON); BRPX = release point (output turns OFF).
 3. Typical Data is at $T_A = 25^\circ C$ and $V_{SUPPLY} = 3.0V$.

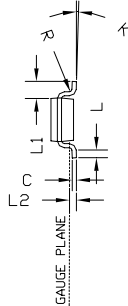
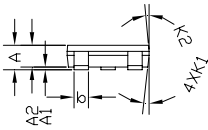
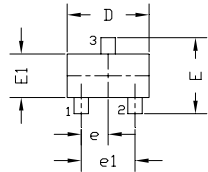
Magnetic Characteristics

Over operating voltage and temperature range unless otherwise noted.

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Operating Points	BOPS	South pole to branded side			60	G
	BOPN	North pole to branded side	-60			G
Release Points	BRPS	South pole to branded side	6			G
	BRPN	North pole to branded side			-6	G
Hysteresis	BHYS	$ BOPX - BRPX $		5		G

- Notes: 1. As use here, negative flux densities are defined as less than zero (algebraic convention) and -50G is less than +10G.
 2. BOPX = operating point (output turns ON); BRPX = release point (output turns OFF).
 3. Typical Data is at $T_A = 25^\circ C$ and $V_{SUPPLY} = 3.0V$.

TSOT23 - 3 LEAD



3. PACKAGE TOP MAY BE SMALLER THAN PACKAGE BOTTOM. DIMENSIONS D AND E1 ARE DETERMINED AT THE OUTERMOST EXTREME OF THE PLASTIC BODY EXCLUDING MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN TOP AND BOTTOM OF THE PLASTIC BODY.
2. DIMENSION "E" DOES NOT INCLUDE INTER-LEAD FLASH OR PROTRUSIONS. INTER-LEAD FLASH AND PROTRUSION SHALL NOT EXCEED .006" (0.15MM) PER SIDE.
1. DIMENSION "D" DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS AND GATE BURRS SHALL NOT EXCEED .004 IN. (0.10MM) PER SIDE.

NOTES: (UNLESS OTHERWISE SPECIFIED)

DIM.	DIMENSIONS					
	INCH			MILLIMETER		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.030	-	0.035	0.75	-	0.90
A1	0.000	-	0.004	0.00	-	0.10
A2	0.028	0.030	0.031	0.70	0.75	0.80
b	0.014	-	0.020	0.35	-	0.51
c	0.004	-	0.010	0.10	-	0.25
D	0.110	0.114	0.118	2.80	2.90	3.00
E	0.102	0.110	0.118	2.60	2.80	3.00
E1	0.059	0.063	0.067	1.50	1.60	1.70
e	0.0374 BSC			0.95 BSC		
e1	0.0748 BSC			1.90 BSC		
L	0.015	-	-	0.37	-	-
L1	0.0236 REF			0.60 REF		
L2	0.0098 BSC			0.25 BSC		
y	-	-	0.004	-	-	0.10
R	0.004	-	-	0.10	-	-
K	0°	-	8°	0°	-	8°
K1	7° NOM			7° NOM		
K2	5° NOM			5° NOM		

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Specification: MX887P
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